

### **Additive Processing**

<u>Resist</u>	<u>Thickness</u>
NR4-8000P	6.0µm - 20.0µm
NR21-20000P	18.0µm - 200µm
Temperature resistance = 100°C. NR9 series resists offer enhanced adhesion and are easily strippable at 25°C.	

High aspect ratio plating for the fabrication of bumps for flip-chip packaging, multi-chip modules, MEMS, sensors, thin-film magnetic heads

#### Properties for Additive Applications

- Superb adhesion during plating
- Easy removal with Futurrex resist strippers after plating
- Sensitivity to wavelengths shorter than 380nm

#### Impact on productivity

- Elimination of solvent-based development and solvent-based rinse processing steps

#### Features

- superb linewidth control over surface topology
- straight sidewalls for any film thickness
- capability to apply 100 µm thick film in a single spin coating
- superior resolution capability in thick film applications
- superior photospeed enhancing exposure throughput
- facilitates increased power density in RIE/ion milling, which boosts etch rate and etch throughput
- application of a single developer for both negative and positive resists
- elimination of use of adhesion promoters

